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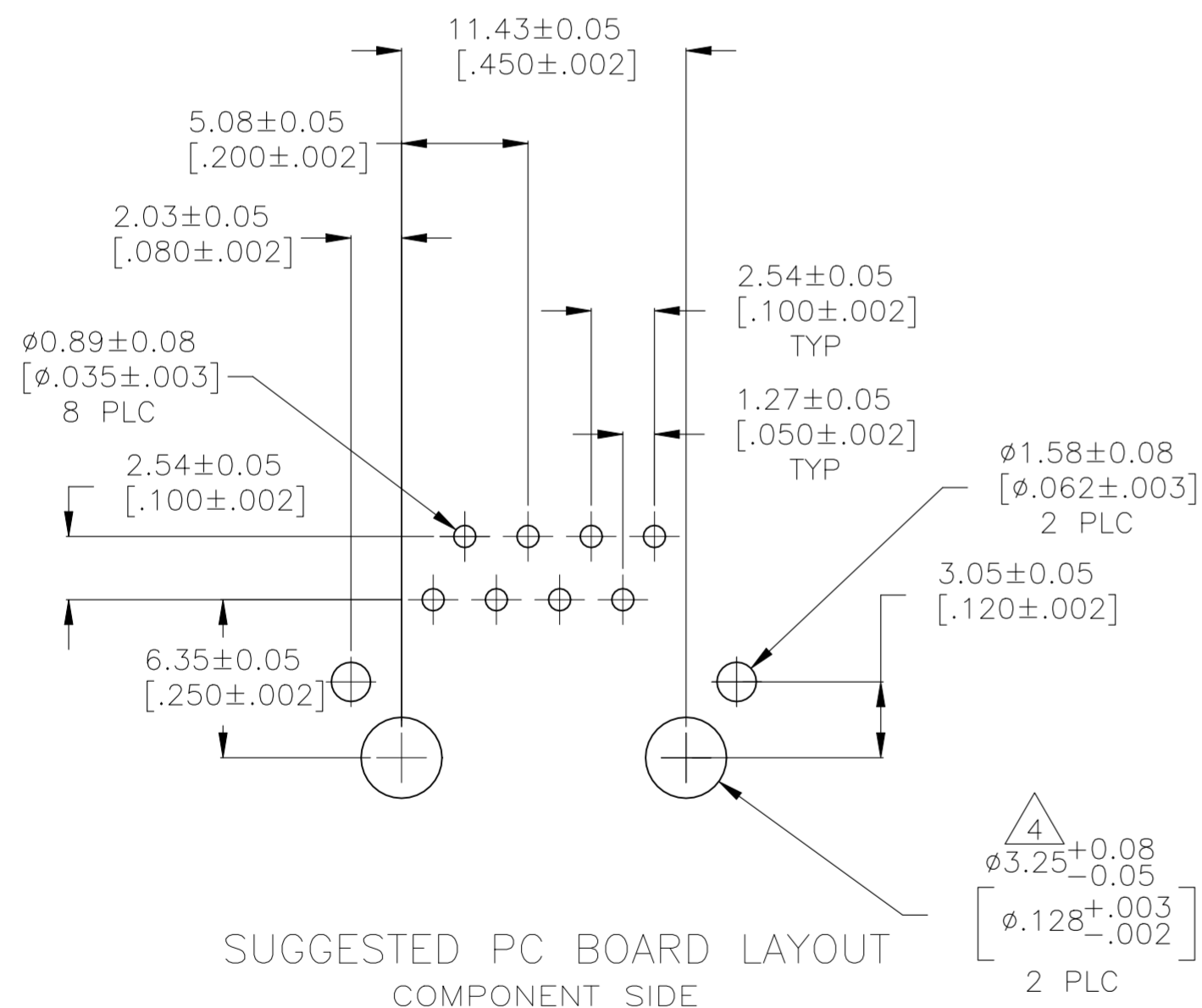
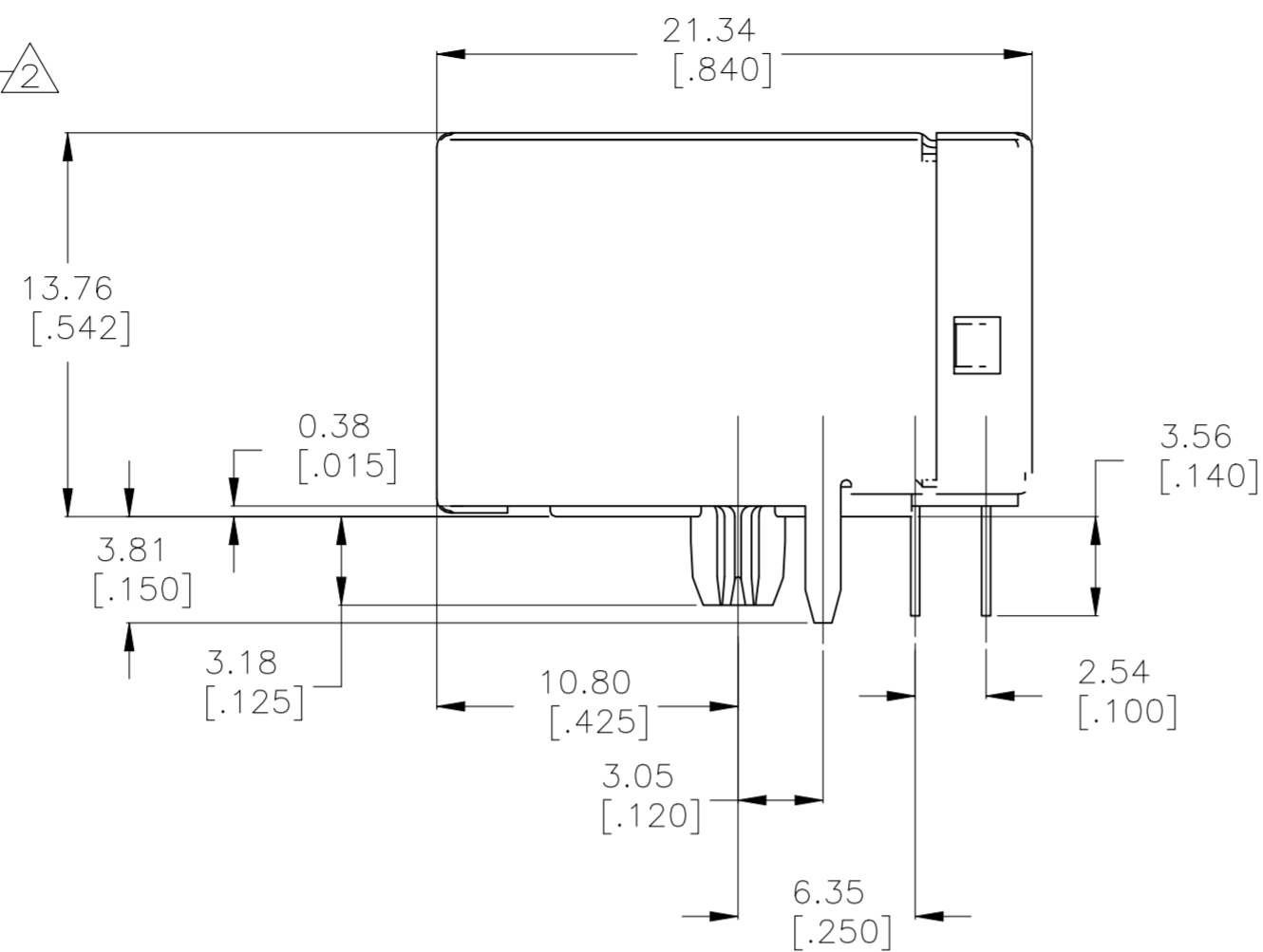
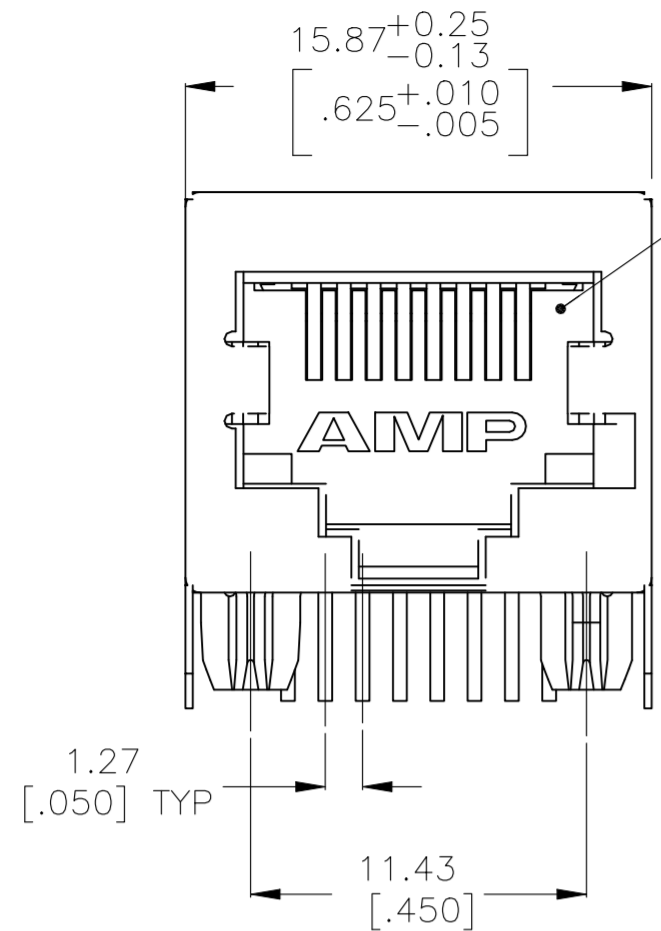
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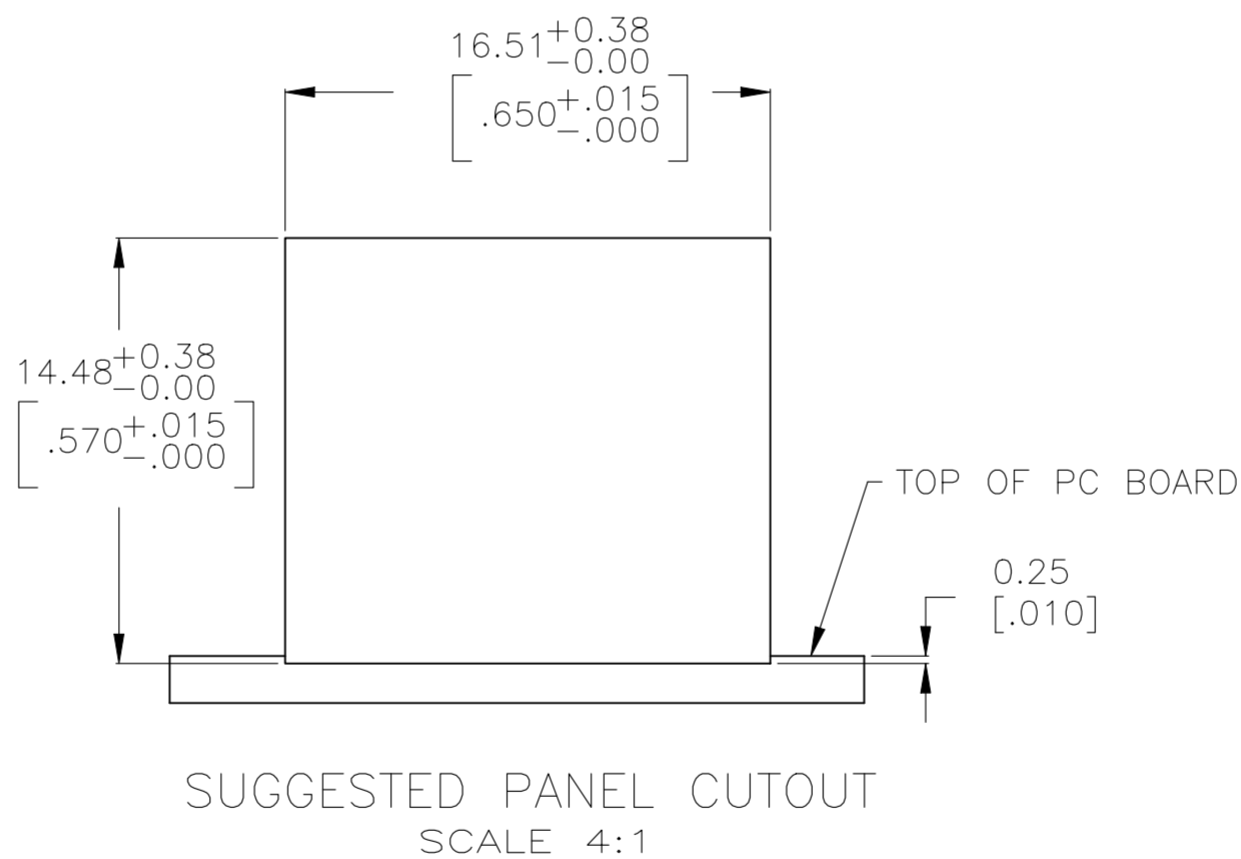
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REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
	F1	ECR-19-014657	13DEC2020	RR	SZ

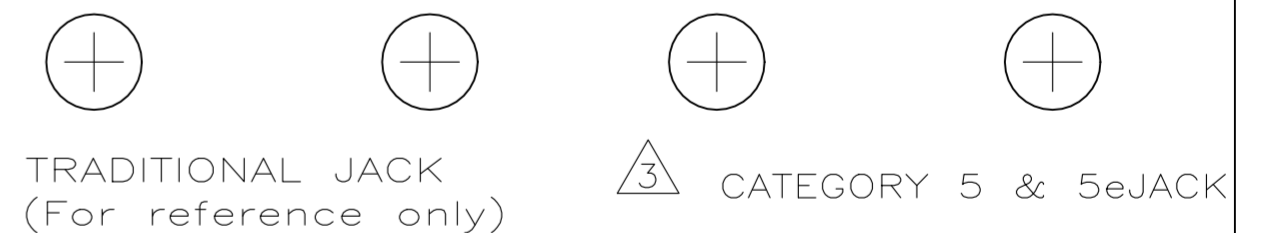


SUGGESTED PC BOARD LAYOUT COMPONENT SIDE



- MATERIAL: HOUSING HTN, BLACK.
TERMINALS - 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81µm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MINIMUM THICK NICKEL UNDERPLATE.
SHIELDS - 0.254[.010] THICK COPPER ALLOY PLATED WITH 1.27µm[.000050] MINIMUM NICKEL AND 2.03 µm [.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.

- △ JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- △ CAUTION: CATEGORY 5 JACK SOLDER TAIL POSITIONS DO NOT FOLLOW SAME NUMBER SEQUENCE AS THAT OF TRADITIONAL JACKS.
- △ USE #30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PCB HOLES.
- △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI
- △ SHIELD MATERIAL: PHOS BRONZE.



	△ BLACK	5558342-3
△ OBSOLETE	GRAY	5558342-2
	BLACK	5558342-1
	HOUSING COLOR	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN T. PITTS/LA.MAYER 01JUNE2005	TE TE Connectivity		
		CHK J.WESTMAN 01JUNE2005			
DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	APVD S.FLICKINGER 01JUNE2005	NAME	MODULAR JACK ASY, 8 POSN, R/σ,LOW PROFILE,SHIELDED, PC BOARD GROUND,CATEGORY 5e	
	0 PLC ± - 1 PLC ± - 2 PLC ± 0.25[.010] 3 PLC ± - 4 PLC ± - ANGLES ± -	PRODUCT SPEC 108-1163-2	APPLICATION SPEC 114-2048	SIZE	RESTRICTED TO
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	WEIGHT 0.000000	A2 00779	CAGE CODE 5558342	SCALE 4:1 SHEET 1 OF 1 REV F1
CUSTOMER DRAWING					

5558342

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